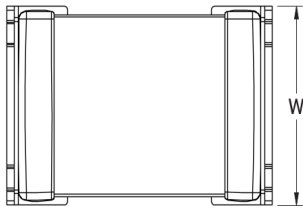


TOP VIEW
Single or Double Chip Stack



PROFILE VIEW
Single Chip Stack



Click [here](#) for the 3D model.

Dimensions

| | |
|---|------------------|
| L | 3.5mm +/-0.3mm |
| W | 2.6mm +/-0.3mm |
| T | 3.35mm +/-0.10mm |
| B | 0.8mm +/-0.15mm |

Packaging Specifications

| | |
|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 600 |

General Information

| | |
|------------------|---|
| Series | KPS SMD Comm X8L HT150C |
| Style | Stacked Chip |
| Description | SMD, MLCC, Stacked, Single Chip, High Temperature |
| Features | High Temperature |
| RoHS | Yes |
| Termination | Tin |
| AEC-Q200 | No |
| Component Weight | 160 mg |
| Chip Size | 1210-1 |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|---|
| Capacitance | 1 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 10% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+150°C |
| Temperature Coefficient | X8L |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | +15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms |
| Dissipation Factor | 2.5% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 500 MOhms |